

**PATENT ASSIGNMENT**

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 Stylesheet Version v1.1

|  |   |
|--|---|
| SUBMISSION TYPE:   | NEW ASSIGNMENT                              |
| NATURE OF CONVEYANCE:  | ASSIGNMENT                                  |
| <b>CONVEYING PARTY DATA</b>  |   |
| <b>Name</b>  | <b>Execution Date</b>                       |
| Jung-Soo BYUN  | 11/23/2010                                  |
| Yul-Kyo CHUNG  | 11/23/2010                                  |
| Hwa-Sun PARK   | 11/23/2010                                  |
| Kyung-Min LEE  | 11/23/2010                                  |
| Mike KIM   | 11/23/2010                                  |
| Doo-hwan LEE   | 11/23/2010                                  |
| <b>RECEIVING PARTY DATA</b>  |   |
| <b>Name:</b>   | SAMSUNG ELECTRO-MECHANICS CO., LTD.         |
| <b>Street Address:</b>   | 314, Maetan3-Dong, Yeongtong-Gu             |
| <b>City:</b>   | Suwon, Gyunggi-Do                           |
| <b>State/Country:</b>  | KOREA, DEMOCRATIC PEOPLE'S REPUBLIC OF      |
| <b>Postal Code:</b>  | 443-743                                     |
| <b>PROPERTY NUMBERS Total: 1</b>   |   |
| <b>Property Type</b>   | <b>Number</b>                               |
| Application Number:  | 12915707                                    |
| <b>CORRESPONDENCE DATA</b>   |   |
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| <b>ATTORNEY DOCKET NUMBER:</b>   | 075951-0238                                 |
| <b>NAME OF SUBMITTER:</b>  | Stephen A. Becker                           |

CH \$40.00 12915707

**501399847**

**PATENT**  
**REEL: 025600 FRAME: 0438**

Total Attachments: 3

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RECORDATION FORM COVER SHEET

**Docket No.: 075951-0238**

**PATENTS ONLY**

To the Director of the U. S. Patent and Trademark Office: Please record the attached documents or the new address(es) below.

**1. Name of Conveying Party(ies)**  
**Jung-Soo BYUN, Yul-Kyo CHUNG, Hwa-Sun PARK, Kyung-Min LEE, Mike KIM, Doo-hwan LEE**

Additional name(s) of conveying party(ies) attached?  Yes  No

**2. Name and address of receiving party(ies)**  
 Name: **SAMSUNG ELECTRO-MECHANICS CO., LTD.**  
 Internal Address:  
 Address: **314, Maetan3-Dong, Yeongtong-Gu, Suwon, Gyunggi-Do 443-743 REPUBLIC OF KOREA**

Additional name(s) & address(es) attached?  Yes  No

**3. Nature of Conveyance/Execution Date(s)**

Execution Date(s): **November 23, 2010**

**Assignment**  Merger  
 Security Agreement  Change of Name  
 Joint Research Agreement  
 Government Interest Assignment  
 Executive Order 9424, Confirmatory License  
 Other

**4. Application or patent number(s):**  
 A. Patent Application No(s).  
**12/915,707**

Additional numbers attached?  Yes  No

This document is being filed together with a new application.  
 B. Patent No(s).

**5. Name and address to whom correspondence concerning document should be mailed:**

Name: **MCDERMOTT WILL & EMERY LLP**  
 Internal Address:  
 Street Address: **600 13th Street, N.W.**  
 City: **Washington, DC** State: **DC** Zip: **20005-3096 D.C.**  
 Phone Number: **202.756.8000**  
 Fax Number: **202.756.8087**  
 Email Address:

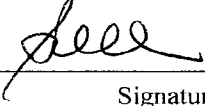
**6. Total number of applications and patents involved:** **1**

**7. Total fee (37 CFR 1.21(h) & 3.41)** **\$40.00**

Authorized to be charged by credit card  
 Authorized to be charged to deposit account  
 Enclosed  
 None required (government interest not affecting title)

**8. Payment Information:**

a. Credit Card Last 4 Numbers \_\_\_\_\_  
 Expiration Date \_\_\_\_\_  
 b. Deposit Account Number **500417**  
 Authorized User Name \_\_\_\_\_

**9. Signature.**  
**Stephen A. Becker 26,527**  **January 7, 2011**

Name and Registration No. of Person Signing \_\_\_\_\_ Signature \_\_\_\_\_ Date \_\_\_\_\_

Total number of pages including cover sheet, attachments and documents: **3**

Docket No.:

**ASSIGNMENT**

In consideration of the premises and other good and valuable consideration in hand paid, the receipt and sufficiency of which is hereby acknowledged, the undersigned,

- |                   |      |       |
|-------------------|------|-------|
| (1) Jung-Soo BYUN | (7)  | _____ |
| (2) Yul-Kyo CHUNG | (8)  | _____ |
| (3) Hwa-Sun PARK  | (9)  | _____ |
| (4) Kyung-Min LEE | (10) | _____ |
| (5) Mike KIM      | (11) | _____ |
| (6) Doo-hwan LEE  | (12) | _____ |

who have made a certain new and useful invention, hereby sell, assign and transfer unto

SAMSUNG ELECTRO-MECHANICS CO., LTD.

its successors and assigns (hereinafter designated "ASSIGNEE") the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100 in the invention entitled

**Electronic components embedded PCB**

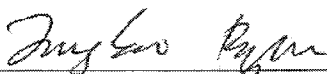

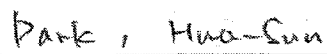
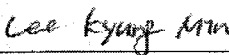
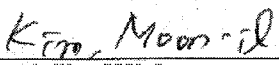
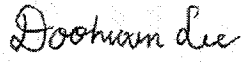
(a) for which an application for United States Letters Patent was filed on \_\_\_\_\_, and identified by United States Serial No. \_\_\_\_\_; or

(b) for which an application for United States Letters Patent was executed on \_\_\_\_\_,

and the undersigned hereby authorize and request the United States Commissioner for Patents and Trademarks to issue any and all United States Letters Patent which may be granted therefor and any and all extensions, divisions, reissues, substitutes, renewals, continuations, or continuations-in-part thereof, and the right to all benefits under the International Convention for the Protection of Industrial Property to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agree that the attorneys of record in said application shall hereafter act on behalf of said ASSIGNEE;

AND the undersigned hereby agree to transfer a like interest, and to render all necessary assistance in making application for and obtaining original, divisional, reissued or extended Letters Patent of the United States, upon request of the said ASSIGNEE, its successors, assigns and legal representatives, and without further remuneration, in and to any improvements, and applications for patent based thereon, growing out of or related to the said invention; and to execute any papers by the said ASSIGNEE, its successors, assigns and legal representatives, deemed essential to ASSIGNEE's full protection and title in and to the invention hereby transferred.

SIGNED on the dates indicated aside our signatures:

| INVENTORS   | DATE SIGNED   |
|---|---------------|
| 1) <br>Name: Jung-Soo BYUN | Nov. 23, 2010 |
| 2) <br>Name: Yul-Kyo CHUNG | Nov. 23, 2010 |
| 3) <br>Name: Hwa-Sun PARK  | Nov. 23, 2010 |
| 4) <br>Name: Kyung-Min LEE | Nov. 23, 2010 |
| 5) <br>Name: Mike KIM      | Nov. 23, 2010 |
| 6) <br>Name: Doo-hwan LEE | Nov. 23, 2010 |